

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISOW7840DWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840
ISOW7840DWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840
ISOW7840DWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840
ISOW7840DWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840
ISOW7840DWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840
ISOW7840FDWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840F
ISOW7840FDWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840F
ISOW7840FDWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840F
ISOW7840FDWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840F
ISOW7840FDWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7840F
ISOW7841DWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841
ISOW7841DWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841
ISOW7841DWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841
ISOW7841DWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841
ISOW7841DWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841
ISOW7841FDWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841F
ISOW7841FDWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841F
ISOW7841FDWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841F
ISOW7841FDWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841F
ISOW7841FDWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7841F
ISOW7842DWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842
ISOW7842DWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842
ISOW7842DWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842
ISOW7842DWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842
ISOW7842DWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842
ISOW7842FDWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842F
ISOW7842FDWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842F
ISOW7842FDWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842F
ISOW7842FDWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842F

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISOW7842FDWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7842F
ISOW7843DWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843
ISOW7843DWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843
ISOW7843DWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843
ISOW7843DWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843
ISOW7843FDWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843F
ISOW7843FDWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843F
ISOW7843FDWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843F
ISOW7843FDWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7843F
ISOW7844DWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844
ISOW7844DWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844
ISOW7844DWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844
ISOW7844DWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844
ISOW7844DWERG4.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844
ISOW7844FDWE	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844F
ISOW7844FDWE.Z	Active	Production	SOIC (DWE) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844F
ISOW7844FDWER	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844F
ISOW7844FDWER.Z	Active	Production	SOIC (DWE) 16	2000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7844F

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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